



# Obsolescence Report

August 2024



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# Semiconductor Obsolescence Report

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Company	Component	Status	Replacement	Reason
AMD	Radeon RX 500 Series GPUs	End of Life	Radeon RX 6000 Series	Shift to newer architecture for better performance and power efficiency.
	Ryzen 5 3600	End of Life (EOL)	Ryzen 5 7600X and newer	Shift to newer architecture for better performance and power efficiency.
	Radeon RX 5700 XT	Discontinued	Radeon RX 7800 XT and newer	Focus on newer GPU models with improved performance and features
Company	Component	Status	Replacement	Reason
Broadcom	Ethernet PHY Chips	End of Life	25G, 40G, 100G Ethernet PHYs	Migration to higher-speed Ethernet standards.
	BCM4339 Wi-Fi Chip	End of Life (EOL)	BCM43684 or newer	Newer chips offer improved connectivity and features
	BCM54616 Ethernet PHY	Discontinued	BCM54640 or newer	Replacement by updated PHYs for better performance and energy efficiency
Company	Component	Status	Replacement	Reason
Infineon	Discrete IGBTs	Discontinued	Integrated Power Modules (IPMs)	Shift towards more integrated and efficient power solutions.
	XMC4500 Micro controller	End of Life (EOL)	XMC4700 series	Superseded by newer micro controllers with advanced features
	IRF540N MOSFET	Discontinued	IRF540N-01 or newer models	Replacement by updated MOSFETs with improved specs
Company	Component	Status	Replacement	Reason
Intel	DDR3 Memory Chips	End of Life	DDR4, DDR5	Transition to faster and more efficient memory technologies.
	Core i7-9700K	End of Life (EOL)	Core i7-12700K and newer	Transition to newer generations with improved specs and performance
	Xeon E5-2680 v4	Discontinued	Xeon Scalable (3rd Gen)	Replacement with newer Xeon processors for better performance and features
Company	Component	Status	Replacement	Reason
Microchip	PIC16F84	End of Life (EOL)	PIC16F88 or newer	Superseded by newer, more advanced PIC micro controllers
	MCP3208 ADC	Discontinued	MCP3204 or newer	Newer ADCs offer better performance and features
Company	Component	Status	Replacement	Reason
Murata	Ceramic Capacitors (older series)	Discontinued	New High-Frequency MLCCs	Market demand for higher frequency and smaller form-factor components.



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Company	Component	Status	Replacement	Reason
NXP Semi-conductors	LPC1768 Micro controller	End of Life (EOL)	LPC177x/8x series	Superseded by newer micro controllers with enhanced capabilities
	PN532 NFC Controller	Discontinued	PN7150 or newer	Newer NFC controllers offer improved performance and features
	Standard Analogue Integrated Circuits	Discontinued	Custom ICs	Declining demand for traditional analogue circuits in industrial applications.
Company	Component	Status	Replacement	Reason
ON Semi-conductor	Bipolar Power Transistors	End of Life	RoHS-compliant transistors	Regulatory changes require environmentally compliant designs.
	NCP1200 Voltage Regulator	End of Life (EOL)	NCP1200-01 or newer	Replacement by updated voltage regulators with better performance and features
	FSA3157 Analogue Switch	Discontinued	FSA3159 or newer	Newer switches offer improved performance and features
Company	Component	Status	Replacement	Reason
Qualcomm	Snapdragon 400 Series SoCs	End of Life	Snapdragon 600/700 Series	Transition to more advanced 5G and AI-enabled chip sets.
Company	Component	Status	Replacement	Reason
Renesas	RX62N Micro controller	End of Life (EOL)	RX63N series	Superseded by the newer RX63N series with enhanced features
	SH2A Series	Discontinued	SH3 Series or newer	Outdated due to technological advancements
	Legacy MCU Families	End of Life	ARM-based MCUs	Industry-wide shift towards 32-bit architectures
Company	Component	Status	Replacement	Reason
STMicro-electronics	Low-Power Op-Amps	End of Life	Programmable analogue ICs	Adoption of more flexible and programmable analogue solutions.
	STM32F1 Series	End of Life (EOL)	STM32F4 and STM32F7 series	Superseded by the more advanced STM32 series with enhanced capabilities
	L298N Motor Driver	Discontinued	L298P or newer motor drivers	Replacement due to advances in motor driver technology



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Company	Component	Status	Replacement	Reason
TSMC	7nm Process Node Components	End of Life	5nm, 3nm	Focus on advanced nodes for AI and high-performance computing.
	7nm Process Node	End of Life (EOL)	5nm and 3nm process nodes	Transition to more advanced technology for better performance and efficiency
	12nm Process Node	Discontinued	7nm and 5nm process nodes	Phased out in favour of newer process technologies
Company	Component	Status	Replacement	Reason
Vishay	Low-Power Resistors	End of Life	High-Power, Precision Resistors	Industry demand for more accurate and power-efficient components.
	1N4148 Diode	End of Life (EOL)	Newer Schottky diodes	Phased out due to shift to higher efficiency diodes
	IRF540N MOSFET	Discontinued	IRF540N-01 or newer models	Replacement by updated MOSFETs with improved specs



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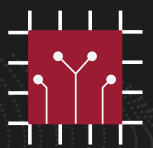
Shortage Management & PPV



Obsolescence Management



Vendor Tail Management



Nuvonix

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## Market Trends and Challenges

### Market Trends

**Continued Growth in AI and ML:** The demand for advanced semiconductors continues to rise due to the expansion of artificial intelligence (AI) and machine learning (ML) applications. This has driven innovations in chip design and manufacturing.

**Expansion of 5G and IoT:** The roll-out of 5G networks and the growth of the Internet of Things (IoT) are fuelling demand for high-performance and specialized semiconductor components.

**Increased Investment in R&D:** Companies are ramping up investment in research and development to create more advanced, energy-efficient, and higher-performing semiconductors.

**Supply Chain Diversification:** In response to past supply chain disruptions, companies are diversifying their supply chains and considering new manufacturing locations.

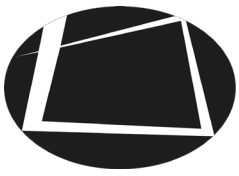
### Challenges

**Supply Chain Disruptions:** The industry continues to face challenges related to supply chain stability and the availability of raw materials, exacerbated by geopolitical tensions and trade restrictions.

**Technological Complexity:** As semiconductor technology advances, the complexity of design and manufacturing processes increases, leading to higher costs and longer development times.

**Regulatory and Trade Issues:** Ongoing regulatory and trade issues, particularly between major markets like the US and China, are affecting the industry's global operations and market dynamics.

**Environmental Impact:** Growing concerns over the environmental impact of semiconductor manufacturing are prompting the industry to seek more sustainable practices and technologies.



## ROM Support Rebound Obsolescence Management Support)

Welcome to Rebound Electronics  
Obsolescence support program.

Obsolescence affects all  
manufactures of long-life cycle  
products. To help mitigate the risk  
to our clients we have put together  
a 5 point proactive and reactive  
approach to a significant issue in  
today's market



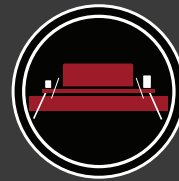
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